

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

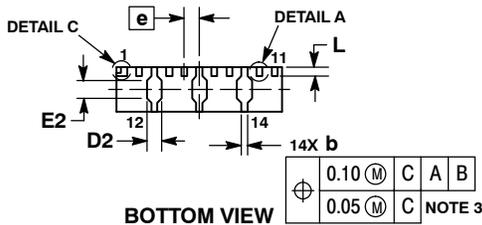
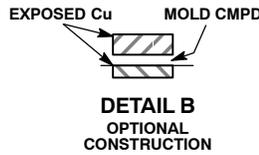
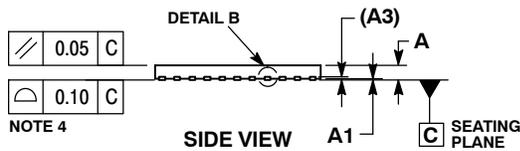
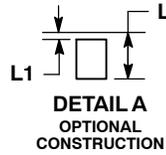
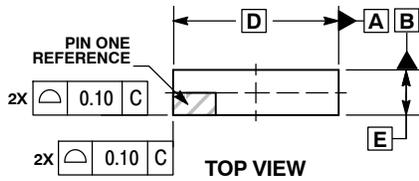
ON Semiconductor®



SCALE 2:1

UDFN14, 5.5x1.5, 0.5P
CASE 517CN
ISSUE O

DATE 30 OCT 2012



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20 MM FROM TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	5.50 BSC	
D2	0.45	0.55
E	1.50 BSC	
E2	0.50	0.70
e	0.50 BSC	
L	0.20	0.40
L1	0.00	0.05

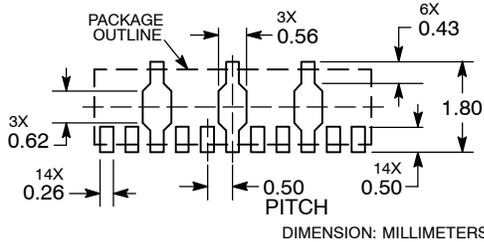
GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	UDFN14, 5.5X1.5, 0.5P	PAGE 1 OF 2

